

IN THE CLAIMS

1. (Currently Amended) A wiring board comprising:
a core substrate defining an opening;
an electronic component;
an embedding resin having a dielectric constant of less than or equal to about 5 and $\tan\delta$ of less than or equal to about 0.08; and
a substrate in which a build-up layer formed by laminating an insulating and a wiring layer in alternate fashion is formed ~~above said embedding resin,~~
wherein, said electronic component is embedded in the opening by said embedding resin,
and
wherein the substrate in which the build-up layer is formed is disposed across the opening and in contiguous contact with the core substrate and the embedding resin.
2. (Original) The wiring board according to claim 1, wherein said embedding resin comprises carbon black in an amount of less than or equal to about 1.4 mass%.
3. (Original) The wiring board according to claim 1, wherein said embedding resin comprises a thermosetting resin as a resin component and at least one inorganic filler.
4. (Original) The wiring board according to claim 3, wherein said thermosetting resin is at least one of a bisphenol-type epoxy resin, a naphthalene-type epoxy resin, a phenol-novolak-type epoxy resin, or a cresol-novolak-type epoxy resin.

5. (Original) The wiring board according to claim 1, wherein said embedding resin assumes a color having a base color tone of black, blue, green, red, orange, yellow, or violet.
6. (Canceled)
7. (Canceled)
8. (New) The wiring board according to claim 1,
wherein the electronic component includes an electrode, and
wherein a distance from the electrode to the wiring layer of the substrate in which the build-up layer formed is less than or equal to 100 μm .
9. (New) The wiring board according to claim 8, wherein the distance from the electrode to the wiring layer of the substrate in which the build-up layer formed is less than or equal to 50 μm .
10. (New) The wiring board according to claim 9, wherein the distance from the electrode to the wiring layer of the substrate in which the build-up layer formed is less than or equal to 30 μm .
11. (New) The wiring board according to claim 1, wherein via holes are formed in the insulating layer.